



Title of Change:	Transfer of Optical Device Chip Scale Package (ODCSP) site from Gunma, Japan to Niigata, Japan and Dicing site change from Shenzhen, China to Tarlac, Philippines.			
Proposed first ship date:	3 December 2016 <i>or earlier upon customer approval</i>			
Contact information:	Contact your local ON Semiconductor Sales Office or <Hiroshi.Kojima@onsemi.com>			
Samples:	Contact your local ON Semiconductor Sales Office			
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Satoru.Fujinuma@onsemi.com>			
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.			
Change Part Identification:	Products manufactured at Niigata and Tarlac will be printed Date Code from 1640 on shipping MPN label.			
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____			
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____			
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Gunma, Japan ON Niigata, Japan ON Tarlac City, Philippines ON Shenzhen, China <input type="checkbox"/> External Foundry/Subcon site(s) _____			
Description and Purpose:				
This Final Change Notification announces that to continuously supply the products and increase our supply capacity to support the increase demands, Optical Device Chip Scale Package (ODCSP) location will be moved from Gunma, Japan to Niigata, Japan and dicing site location will be moved from Shenzhen, China to Tarlac city, Philippines. All equipment and most personnel were transferred from Gunma to Niigata site and most equipment was transferred from Shenzhen to Tarlac site. The Niigata and Tarlac site are ISO/TS16949 certified.				
Reliability Data Summary:				
QV DEVICE NAME: LV0318XA PACKAGE: ODCSP16				
Test	Specification	Condition	Interval	Results
HTOL	EIAJ ED-4701/100	Ta= 70°C , Vcc = operating max	1008 hrs	0/231
HTSL	EIAJ ED-4701/200	Ta= 100°C	1008 hrs	0/231
TC	EIAJ ED-4701/100	Ta= -40°C to +100°C	100 cyc	0/231
THB	EIAJ ED-4701/100	60°C, 90% RH, Vcc = recommended	1008 hrs	0/231



Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
LV0111CF-TLM-H	LV0318XA-NH